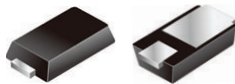


eSMP® Flat Type Surface Mount Packages with Space-Saving Footprints

The Vishay Semiconductors eSMP® flat type surface mount packages enables higher current density and power efficiency with a unique design that promotes better thermal performance and reliability.

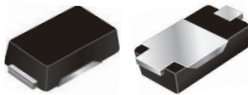
ASYMMETRICAL FLAT TYPES

MicroSMP



(2.5 x 1.3 x 0.65) mm

DO-220AA (SMP)



(3.8 x 2 x 1) mm

DO-221BC (SMPA)



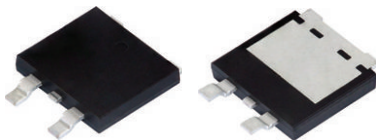
(5.2 x 2.6 x 0.95) mm

TO-277A (SMPC)



(6.7 x 4.8 x 1.1) mm

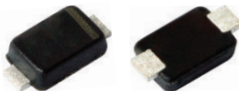
TO-263AC (SMPD)



(12.63 x 10 x 1.7) mm

SYMMETRICAL FLAT TYPES

DO-219AC (MicroSMF)



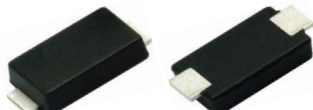
(2.5 x 1.3 x 0.65) mm

DO-219AB (SMF)



(3.7 x 1.8 x 0.98) mm

DO-221AC (SlimSMA™)



(5.2 x 2.6 x 0.95) mm

FEATURES

- Space saving miniature packages:
 - MicroSMP (2.5 x 1.3 x 0.65) mm
 - DO-220AA (SMP) (3.8 x 2 x 1) mm
 - DO-221BC (SMPA) (5.2 x 2.6 x 0.95) mm
 - TO-277A (SMPC) (6.7 x 4.8 x 1.1) mm
 - TO-263AC (SMPD) (12.63 x 10 x 1.7) mm
 - DO-219AC (MicroSMF) (2.5 x 1.3 x 0.65) mm
 - Symmetrical leads
 - Wave and reflow solderable
 - DO-219AB (SMF) (3.7 x 1.8 x 0.98) mm
 - Symmetrical leads
 - Wave and reflow solderable
 - DO-221AC (SlimSMA) (5.2 x 2.6 x 0.95) mm
 - Symmetrical leads
- Special wide bottom plate design enables better heat dissipation than other packages of similar sizes
 - Low device height
 - Low thermal resistance
 - AEC-Q101 qualified
 - Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 HALOGEN
FREE
 Available

APPLICATIONS

- Telecom
- Automotive
- Computer
- Industrial
- Lighting
- DC/DC converters
- Free wheeling
- Mobile consumer electronics
- Solar cell junction box as a bypass diode for protection

	$R_{\theta JM}$
MicroSMP	30 °C/W
DO-220AA (SMP)	15 °C/W
DO-221BC (SMPA)	9 °C/W
TO-277A (SMPC)	3 °C/W
TO-263AC (SMPD)	1 °C/W
DO-219AC (MicroSMF)	38 °C/W
DO-219AB (SMF)	22 °C/W
DO-221AC (SlimSMA)	12 °C/W